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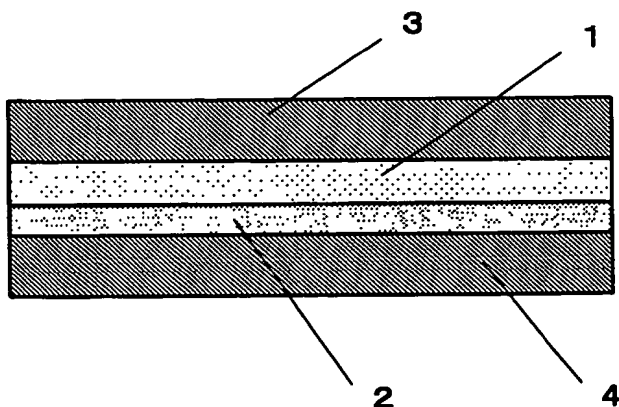
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(54) Title: SILICONE-BASED ADHESIVE SHEET, METHOD OF BONDING A SEMICONDUCTOR CHIP TO A CHIP ATTACHMENT COMPONENT, AND A SEMICONDUCTOR DEVICE



(57) Abstract: A silicone-based adhesive sheet has either a layer of clay-like curable silicone composition on one side and a layer of slower curing clay-like curable silicone composition than the first composition layer on the other side, or a cured silicone layer on one side and a layer of clay-like curable silicone composition on the other side. The silicone-based adhesive sheet may be used in a method for bonding a semiconductor chip and a chip attachment component. A semiconductor device may be prepared by the method.